


ASSEMBLY NOTES:

- 1. ALL COMPONENTS SHALL BE RoHS COMPLIANT.
- 2. ALL UNUSED THROUGH HOLE COMPONENT LOCATIONS SHALL BE FREE OF SOLDER.
- 3. ALL TEST POINT THROUGH HOLES (DENOTED TPxx) SHALL BE FREE OF SOLDER.
- 4. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD, EXCEPT AS NOTED.
- 5. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.
- 6. ALL LEADS SHALL BE TRIMMED TO A MAXIMUM HEIGHT OF 2mm.
- 7. PLACE LABELS ON THE LOCATION INDICATED.

  
**MICROCHIP**  
Microchip Technology Inc.  
2355 W. Chandler Blvd.  
Chandler, AZ 85224

TITLE:

Hillstar Development Kit

PART NUMBER: 10190

ASSEMBLY VARIANT: (No Variations)

PCB DESIGNER:  
Fergus O'Kane

ENGINEER:  
Fergus O'Kane

PCB FILE NAME:  
10190.PcbDoc

GERBER FILE:  
Top Assembly Drawing

BOARD NUMBER:  
04-10190

LAYER NAME:  
Top Assembly (M11)

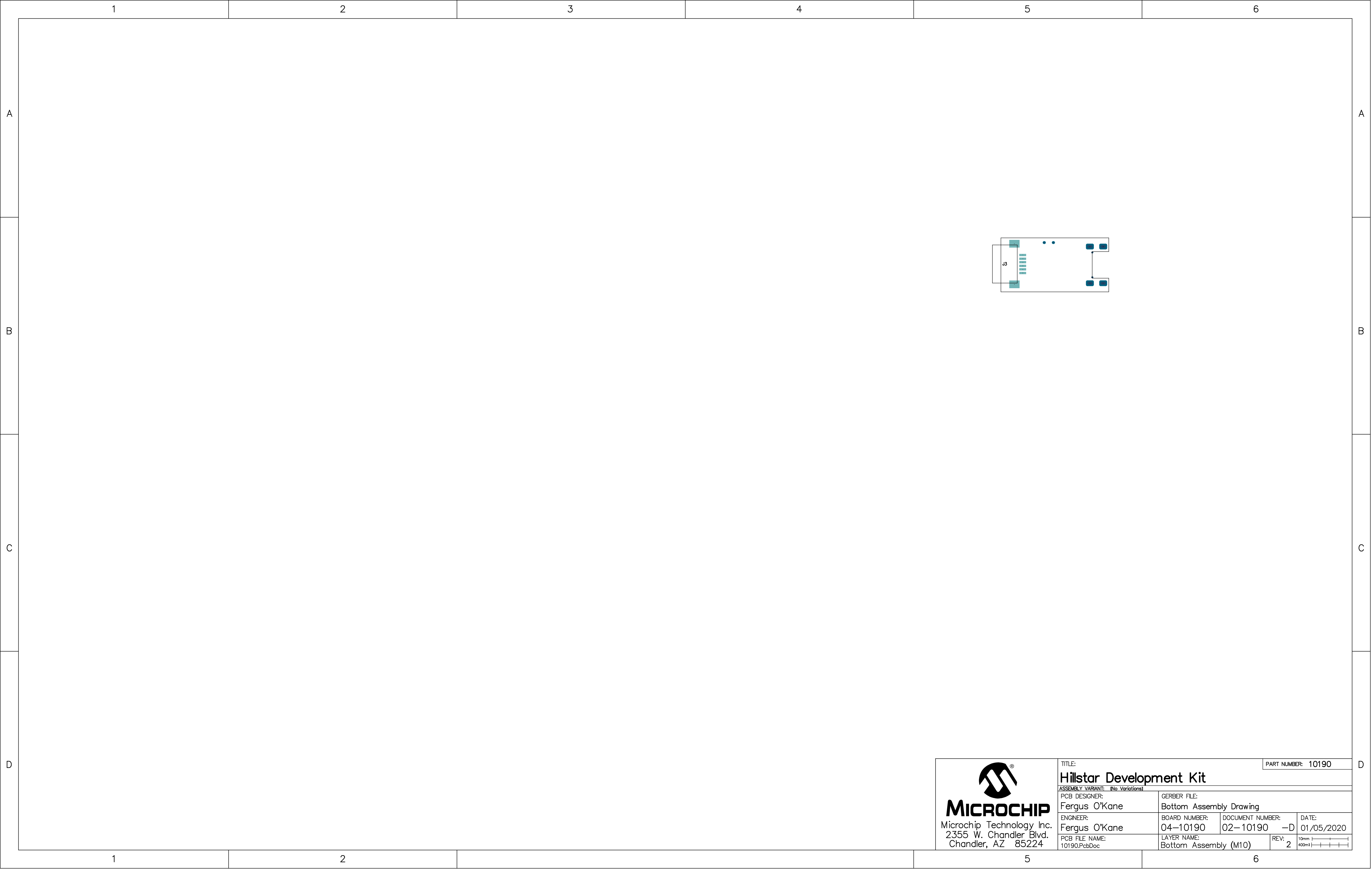
DOCUMENT NUMBER:  
02-10190 -D

DATE:  
01/05/2020

REV: 2

10mm

400mil



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TITLE:		PART NUMBER: 10190	
Hillstar Development Kit			
ASSEMBLY VARIANT: (No Variations)			
PCB DESIGNER: Fergus O'Kane		GERBER FILE: Bottom Assembly Drawing	
ENGINEER: Fergus O'Kane		BOARD NUMBER: 04-10190	DOCUMENT NUMBER: 02-10190 -D
PCB FILE NAME: 10190.PcbDoc		LAYER NAME: Bottom Assembly (M10)	DATE: 01/05/2020
		REV: 2	